



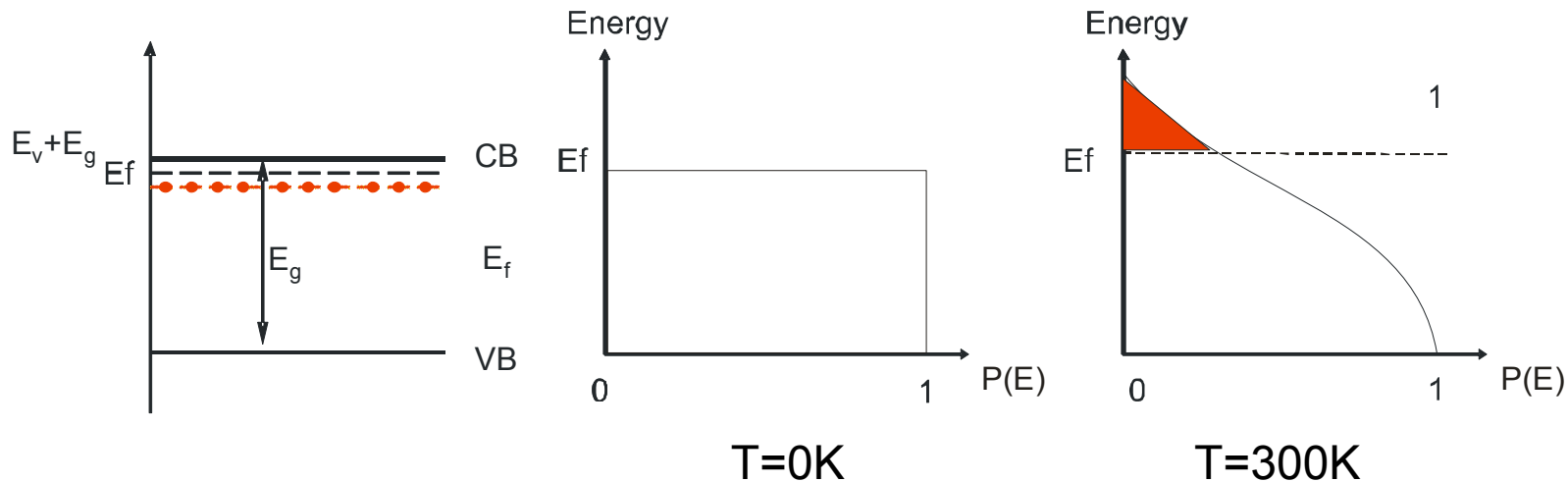
Energy bands & Occupation

Position of the Fermi Level in Doped Semiconductors

Intrinsic semiconductor E_f is mid-gap, $E_g/2$ because $n=p=n_i$

n-type material is characterised by $n(\text{C.B.}) \gg p(\text{V.B.})$
 $n=10^{22} \text{ m}^{-3}$ $p=10^{10} \text{ m}^{-3}$

Some CB states are full, only a few VB states are empty. Since E_f is the probability of occupation this is accounted for by E_f moving up to bottom of C.B.



At $T=0K$, possibility of V.B. electron crossing E_g is negligible. As $T \uparrow$ from $0K$, first electrons to reach C.B. come from donor levels, - so behaves like intrinsic semiconductor with gap reduced to E_i and E_f located at the middle of this gap.

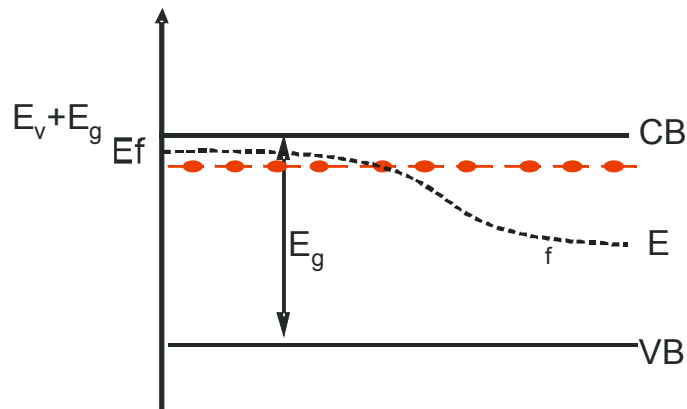


Energy bands & Occupation

At high T ($>300^\circ\text{C}$), intrinsic carriers come in to play.

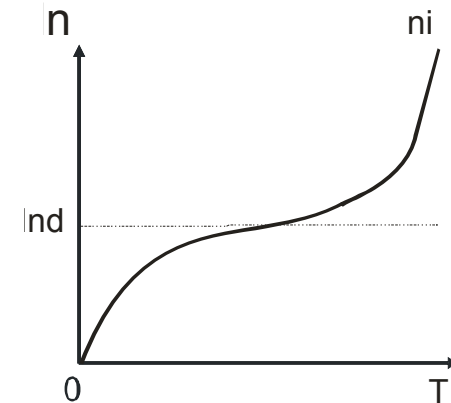
Then $n = N_d +$ 'intrinsic' electrons. This is significant when $kT \gg E_g$

Intrinsic carriers become more dominant, as $T \uparrow E_f$ moves to mid-gap.

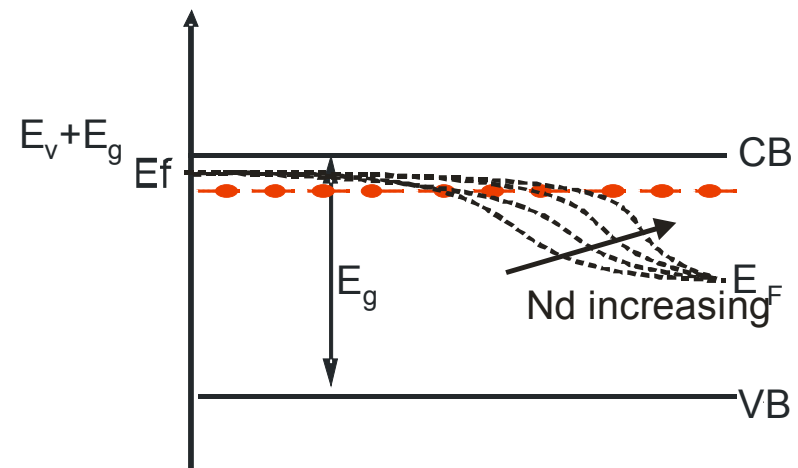


Precise position of E_f is by calculation.

σ_i can be higher than σ_n at very high temperatures, so not true extrinsic behaviour.



As $N_d \uparrow$, 'intrinsic' behaviour sets in at higher temperatures

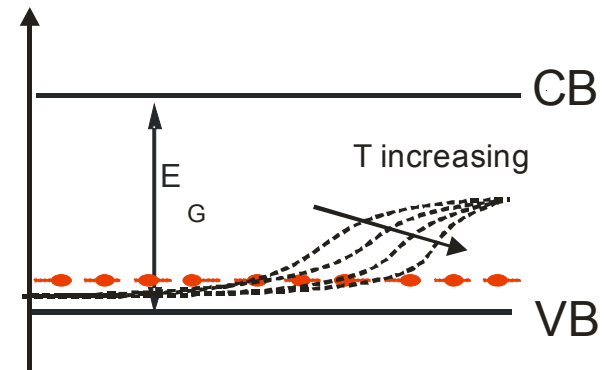




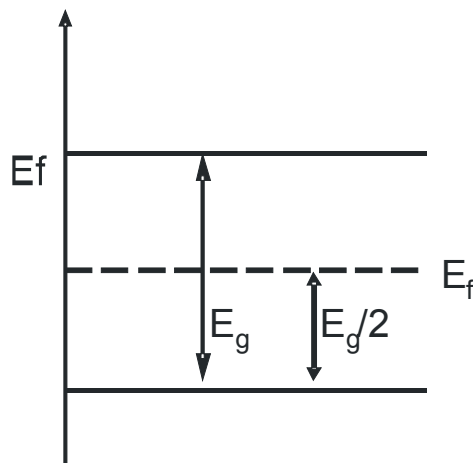
Energy bands & Occupation

P-type

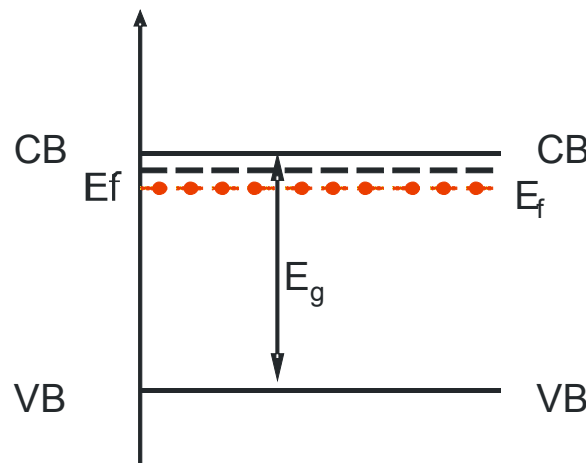
By similar arguments, E_F well below mid-gap and near V.B., only moving towards $E_g/2$ at very high temperature.



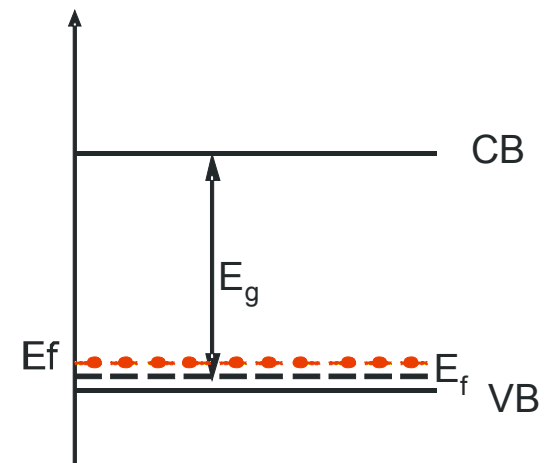
Summary



Intrinsic



n-type



p-type

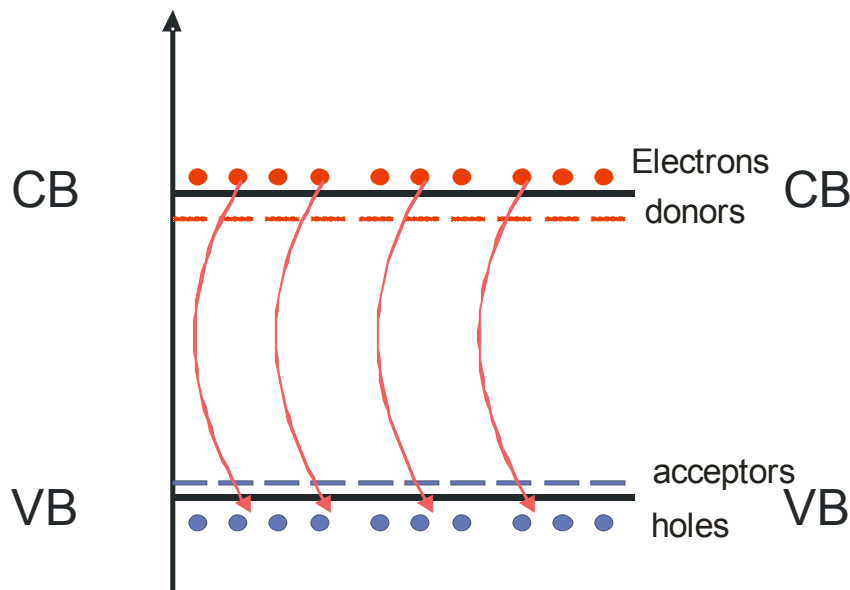


Energy bands & Occupation

Compensation Doping

Occurs when semiconductor is doped with *both* acceptors and donors

Compensation occurs when the extra electrons provided by donors fall into vacancies (or holes) created by acceptors, so if we put N_d donors = N_a acceptors into the silicon, no extra electrons or holes are produced



Why is this important?

Semiconductor wafers are normally doped one type. How to make a device?



Energy bands & Occupation

Consider two of the simplest types of device:
planar diode, planar transistor

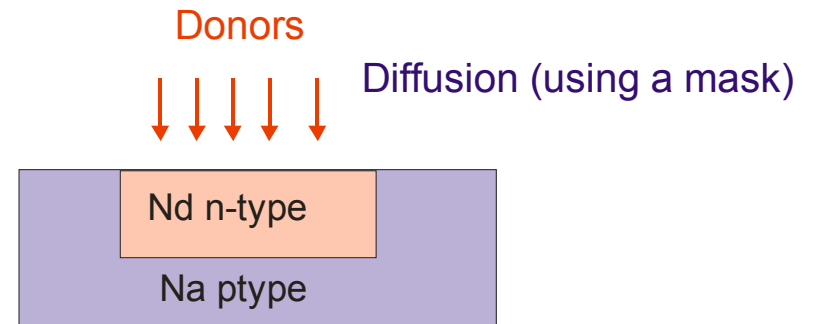
Starting point is a piece of p-type Silicon

These are semiconductors containing N_d and N_a – need to know σ for device design.

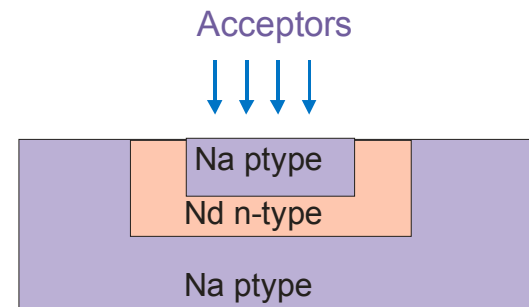
e.g. Si doped with 10^{21}m^{-3} acceptors (N_a)
Then doped with 10^{22}m^{-3} donors (N_d).

All the initial 10^{21} holes from acceptors
recombine with 10^{21} electrons from
donors, leaving the material

n-type $10^{22} - 10^{21} = 9 \times 10^{21} \text{m}^{-3}$ – still a high
concentration.



Planar diode



P-n-p transistor



Energy bands & Occupation

Net density $n(9 \cdot 10^{21}) < N_d (10^{22})$ because of the presence of acceptors – called **compensation**.

Therefore magnitude of $|N_d - N_a|$ determines net carrier density and the sign (+ or -) gives the majority carrier type.

$N_d > N_a$ – n-type

$N_a > N_d$ – p-type

General Case

acceptors
electrons

N_a	N_d
n	p

donors
holes

For electrical neutrality, assuming that T is such that dopants are completely ionised:
negative charge = positive charge

$$n + N_a = p + N_d \quad (3)$$

Always $np = n_i^2 \quad (4)$

Using (3) in (4) $n + (N_a - N_d) = n_i^2/n$

$$n^2 + (N_a - N_d)n - n_i^2 = 0$$

$$n = \frac{(N_d - N_a) \pm \sqrt{(N_d - N_a)^2 + 4n_i^2}}{2}$$

$$n = \frac{(N_d - N_a)}{2} + \frac{(N_d - N_a)}{2} \sqrt{1 + \left(\frac{2n_i}{(N_d - N_a)} \right)^2}$$

carriers from dopants intrinsic carriers



Energy bands & Occupation

For p-type level, use eqn. (4)

$$p = n_i^2 / n$$

can always use this relationship – especially when $n_i \sim (N_d - N_a)$

Case 1: Extrinsic (doped) material

$(N_d - N_a) \gg n_i$ e.g. $10^{22} - 10^{21} \gg 10^{16} \text{m}^{-3}$

2nd term under $\sqrt{\quad} \rightarrow 1$, and

$$n \approx \frac{(N_d - N_a)}{2} + \frac{(N_d - N_a)\sqrt{1}}{2} = N_d - N_a$$

$$p = \frac{n_i^2}{n} = \frac{n_i^2}{N_d - N_a}$$

e.g. $n = 9 \cdot 10^{21} \text{m}^{-3}$, $p \approx 10^{22} \text{m}^{-3}$

If $N_a > N_d$,

$$p = N_a - N_d \text{ AND } n = \frac{n_i^2}{N_a - N_d}$$



Energy bands & Occupation

Case 2: Near Intrinsic Semiconductor

made by doping extrinsic material with just sufficient opposite type dopant to fully compensate and hence produce a net carrier concentration.

Nearly zero e & h from dopants of near zero – carriers then nearly all come from e-h pairs from intrinsic process.

i.e. $n_i \gg |N_d - N_a|$ '1' is negligible in 2nd term under $\sqrt{\quad}$

$$n \approx \frac{(N_d - N_a)}{2} + \frac{(N_d - N_a) \sqrt{\left(\frac{2 n_i}{(N_d - N_a)} \right)^2}}{2}$$

$$n \approx \frac{(N_d - N_a)}{2} + n_i \approx n_i = p$$

Practically it is difficult to get the dopants to cancel exactly to get this condition
e.g. if 10^{22}m^{-3} donors and want to make it intrinsic ($\sim 10^{16} \text{m}^{-3}$), we need to add
acceptors of $1.000001 \times 10^{22} \text{m}^{-3}$ – nearly impossible to control to this
accuracy!



Junction Diode

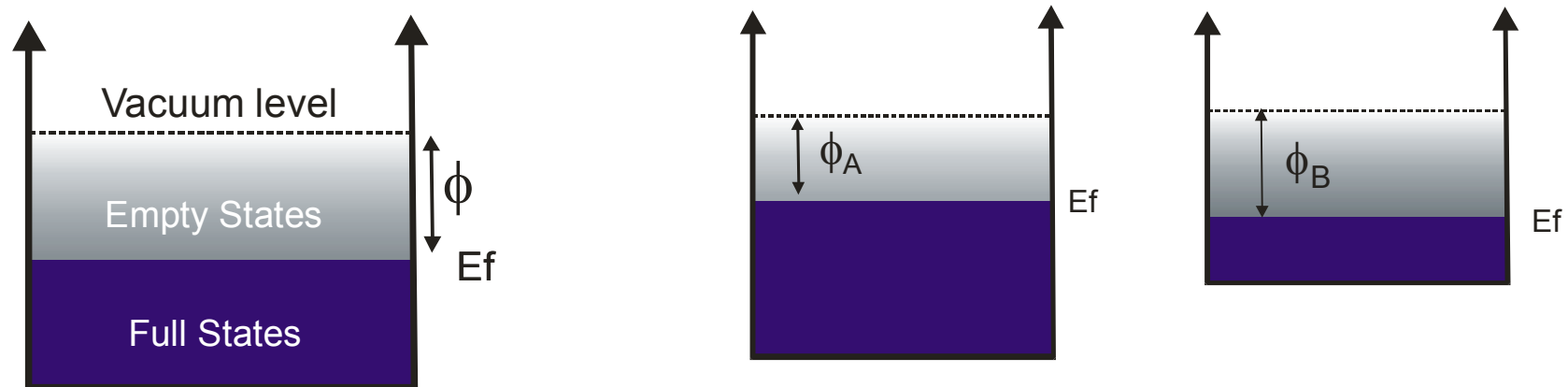
The simplest semiconductor device (but also the basis for the transistor)

Consider the junction in equilibrium (no bias).

In classical electrostatics, 2 bodies in equilibrium have *same* potential – **NOT** true for semiconductor junctions.

For electronic equilibrium, no net current flows – this requires a contact potential to exist between the 2 parts. e.g. p-n junction, V_o

Consider joining two different pieces of material.

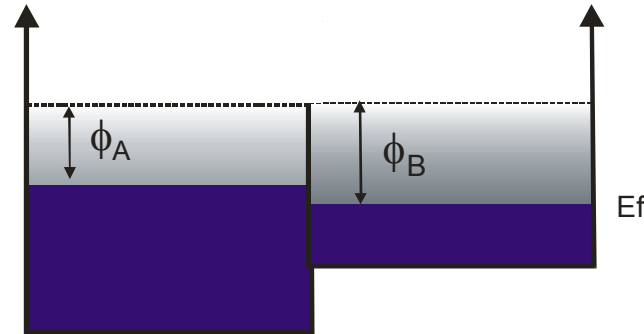


Φ = work function – height of the potential energy barrier at material surface.



Junction Diode

immediately after contact



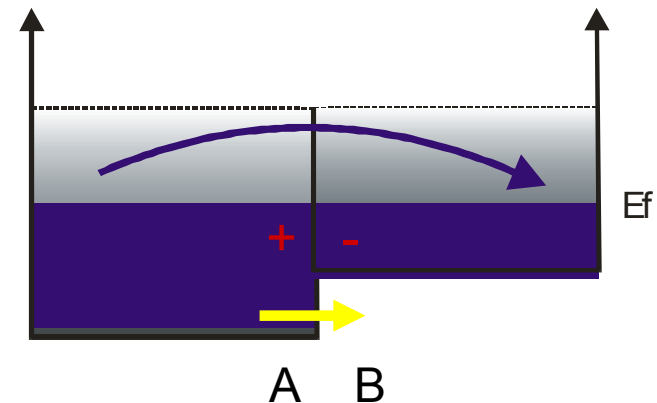
In equilibrium

electron flow from material A (higher Fermi energy level) to material B

No current will flow since the probability of electrons having a particular energy is the same on each side (E_F and T same on each side)

$$P(E) = \frac{1}{1 + \exp\left(\frac{E - E_F}{kT}\right)}$$

E_F is continuous and aligned across the junction. But a contact or built-in potential, V_o , exists to ensure no net flow of electrons.



E-field from built-in potential.



Junction Diode

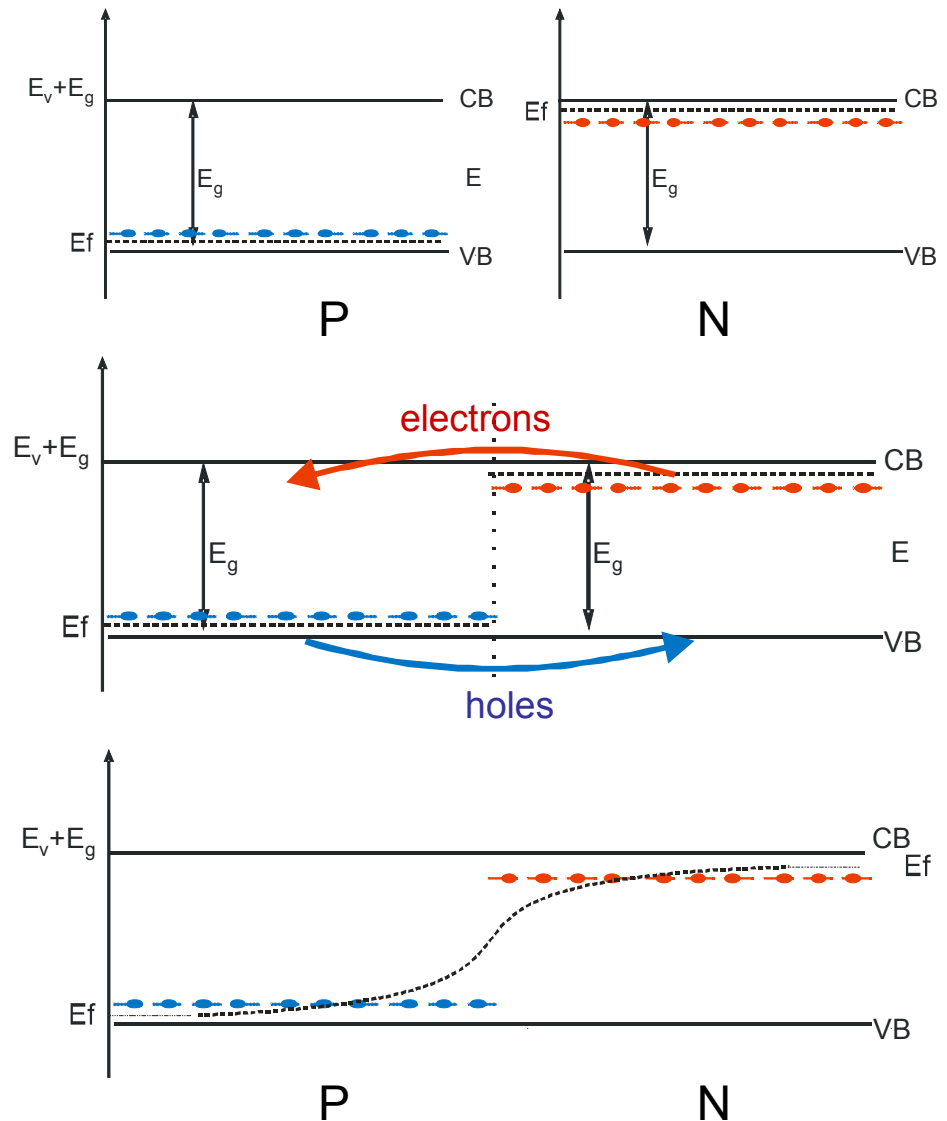
P-N Junction in Equilibrium

Bring 'p' and 'n' semiconductors together to form a junction

At the point of contact

Majority carriers flow across the junction into empty states opposite (diffusion).

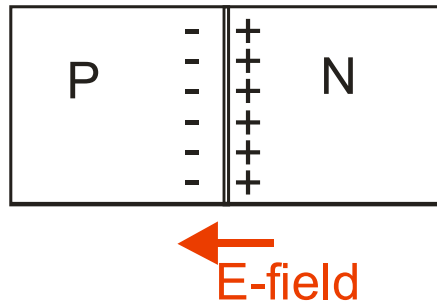
After contact





Junction Diode

As carriers diffuse across, an electric field is created across the junction which eventually balances the flow of carriers. A built in potential, V_0 , appears across the junction



In equilibrium

At equilibrium net current = 0. Hence drift current flow due to the electric field opposes diffusion current flow.

i.e. diffusion current = drift current.

E builds up until net current is zero at equilibrium.

$$E = - \frac{dV}{dx}$$

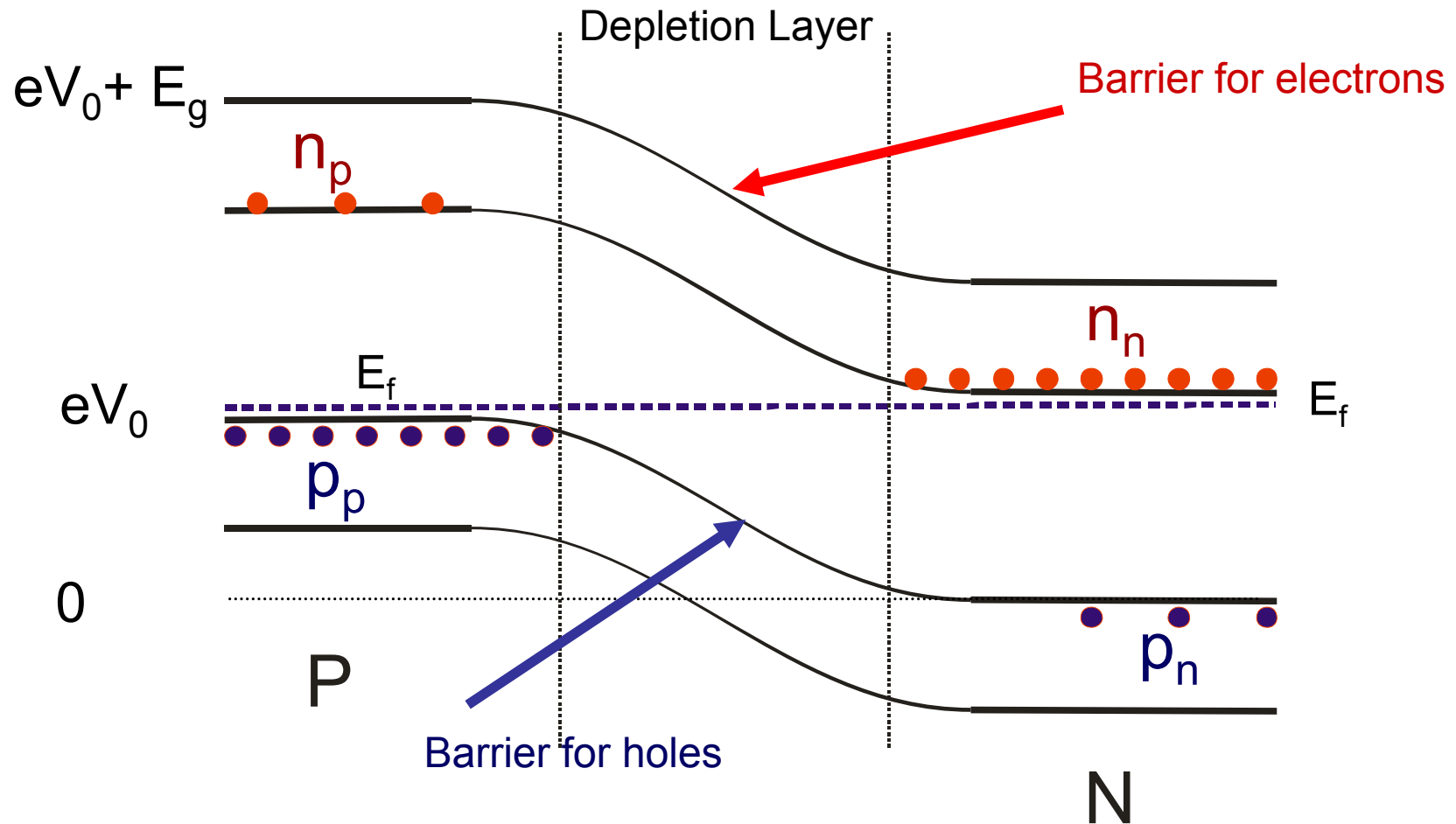
Holes have left the p-region leaving behind fixed negative acceptor charge – **p-levels rise.**

Electrons have left n-region leaving behind fixed positive donor charge – **n levels fall.**



Junction Diode

But C.B., V.B. & E_F are fixed, so alignment only possible if all levels in p-type move relative to those in n-type. Each side of junction takes up a different potential, V_0 .





Junction Diode

The flow of carriers into the opposite side of the junction leaves a charge behind.
This so called space charge (fixed charge) produces the electric field.

A barrier of height eV_o forms due to this electric field which brings the junction into equilibrium and prevents further current flow.

Number of electrons in CB of n-region, $n \propto P(E_g)$

$$n_p \propto \frac{1}{1 + \exp \left(\frac{E_g + eV_o - E_F}{kT} \right)} \propto \exp - \left(\frac{E_g + eV_o - E_F}{kT} \right)$$

Number of the electrons in CB of p-region, $n_p \propto (E_g + eV_o)$

$$n_n \propto \frac{1}{1 + \exp \left(\frac{E_g - E_F}{kT} \right)} \propto \exp - \left(\frac{E_g - E_F}{kT} \right)$$



Junction Diode

Divide the two expressions:

$$\frac{n_n}{n_p} = \exp \left(\frac{eV_o}{kT} \right)$$

$$V_o = \frac{kT}{e} \log_e \left(\frac{n_n}{n_p} \right)$$

Remember that $np = n_i^2$, and therefore $p_p n_p = p_n n_n = n_i^2$

$$n_p = \frac{n_i^2}{p_p}$$

If all carriers are ionized $n_n \approx N_d$ and $p_p \approx N_a$, so by substitution

$$V_o = \frac{kT}{e} \log_e \left(\frac{N_d N_a}{n_i^2} \right)$$



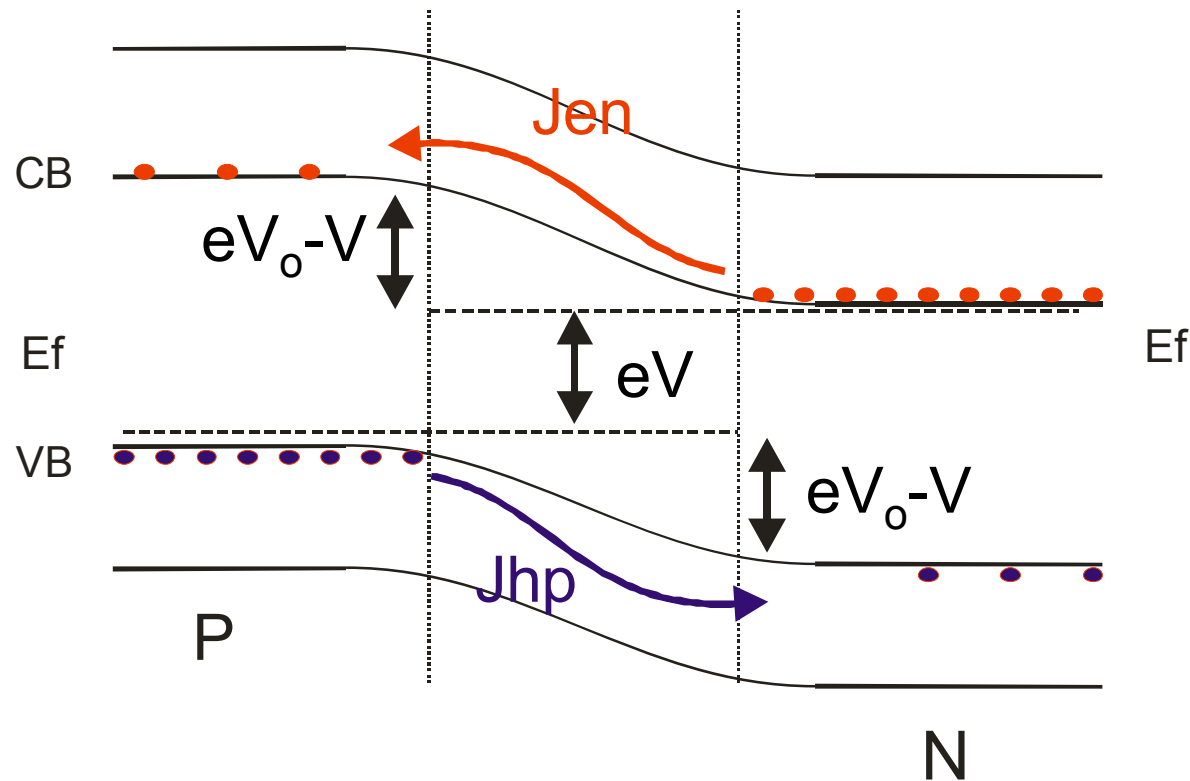
Junction Diode

p-n with different bias conditions

No bias, $I=0$ due to potential barrier (in equilibrium)

Forward bias

With forward bias, V , the barrier height is efficiently reduced to $e(V_0 - V)$. Immediately after bias is applied, energy bands tilt – majority carriers diffuse- current flows (diffusion \neq drift)



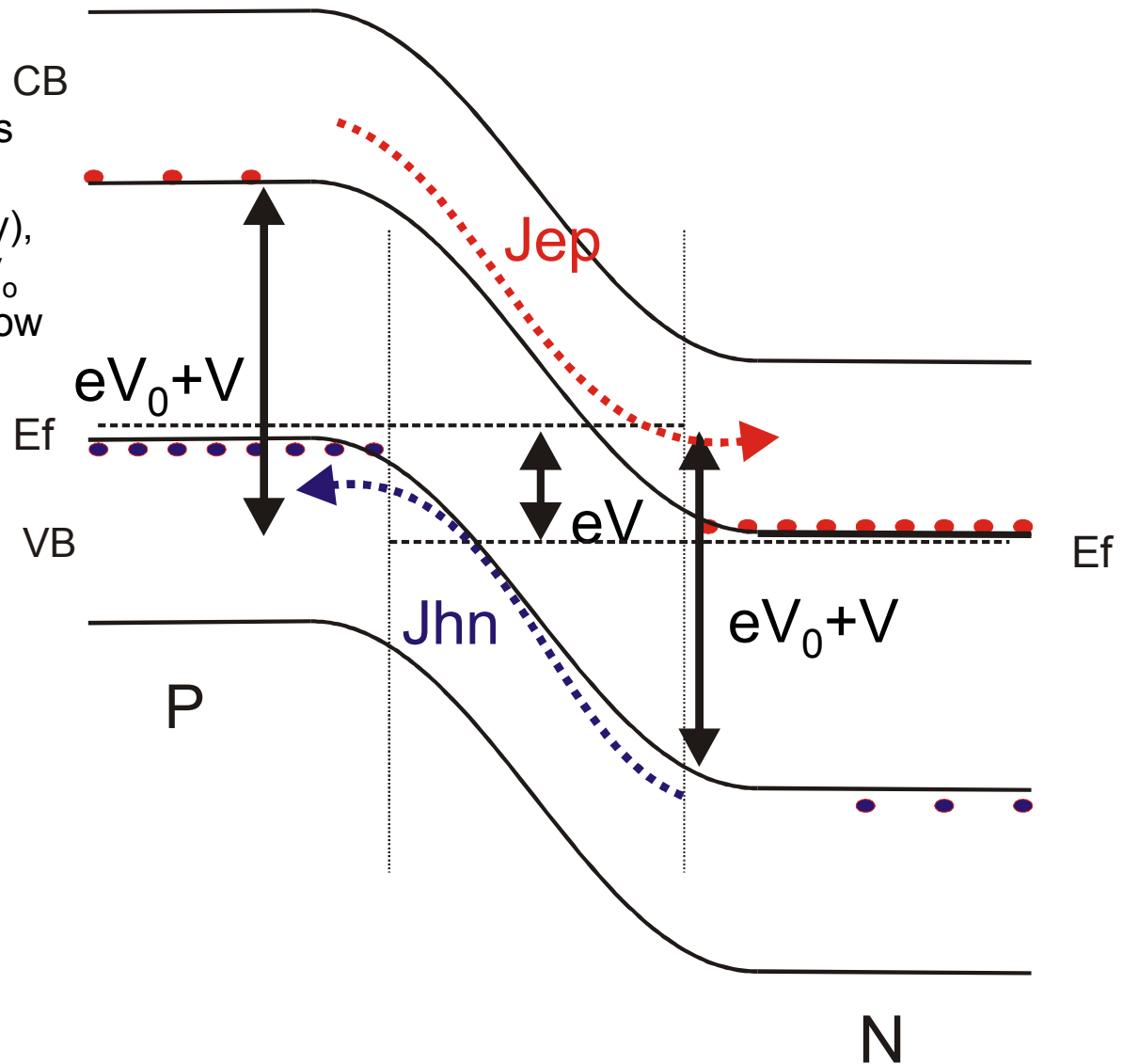


Junction Diode

In steady state, carriers flow from the contacts (external circuit) to restore equilibrium CB away from junction. V appears across depletion layer (fewer carriers so lowers conductivity), lowering barrier height to $e(V_0 - V)$. Large majority current flow

Reverse bias

In steady state, barrier height is increased, $e(V_0 + V)$. No majority carriers flow because of increased barrier height (i.e. diffusion \rightarrow zero).





Junction Diode

Very small electron current flows from p \rightarrow n due to minority electrons, which are swept across by E-field (i.e. fall down potential hill). Similarly for minority holes flow. The small saturation current which does flow is I_o which is independent of V – it depends primarily on temperature.

This leads to the diode (rectifier) equation:

$$I = I_o \left[\exp \left(\frac{eV}{kT} \right) - 1 \right]$$

4 components of current flow in a p-n semiconductor junction.

Majority hole current from p, J_{hp} .

Minority hole current from n, J_{hn}

Minority electron current from p, J_{ep} .

Majority electron current from n, J_{en}

Reverse bias – majority current cannot flow - get minority J_{ep} and J_{hn} as shown – they arise from thermal generation of e-h pairs in or near the depletion region. – depends on temperature.

Zero bias –

When $V=0$, $J_{hp} = J_{hn}$ and $J_{ep} = J_{en}$,

i.e. no current

Forward bias

with $V>0$,

$$J_{hp} = J_{hn} \exp \left(\frac{eV}{kT} \right) \text{ (hole flow)}$$

$$J_{en} = J_{ep} \exp \left(\frac{eV}{kT} \right) \text{ (electron flow)}$$



Junction Diode

$$\text{Net hole current, } J_h = J_{hp} - J_{hn} = J_{hn} \left[\exp\left(\frac{eV}{kT}\right) - 1 \right]$$

$$\text{Net electron current, } J_e = J_{en} - J_{ep} = J_{ep} \left[\exp\left(\frac{eV}{kT}\right) - 1 \right]$$

Total diode current is

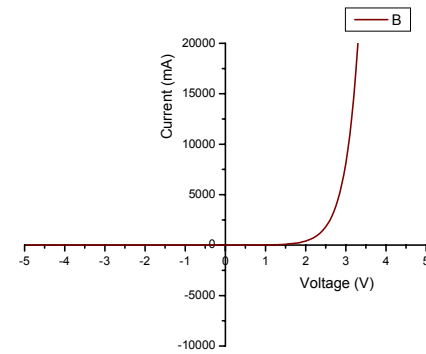
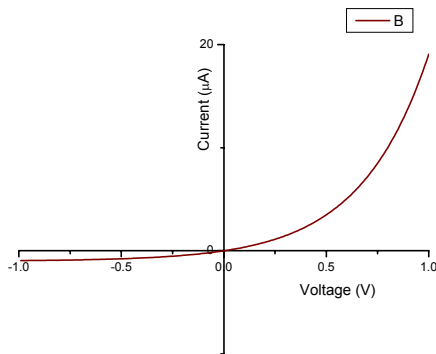
$$J = J_h + J_e = J_o \left[\exp\left(\frac{eV}{kT}\right) - 1 \right]$$



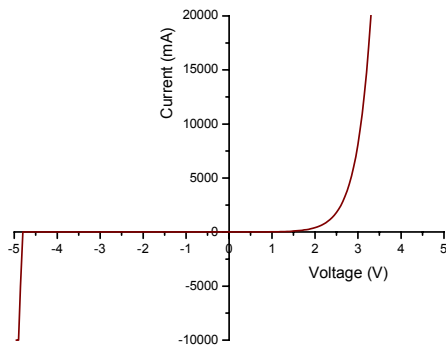
Junction Diode

Ideal Diode Equation

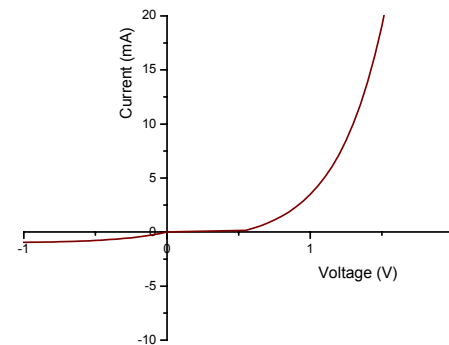
$$J = J_o \left[\exp \left(\frac{eV}{kT} \right) - 1 \right]$$



Deviation from Ideality



Reverse (avalanche) breakdown



Offset (or turn-on) voltage



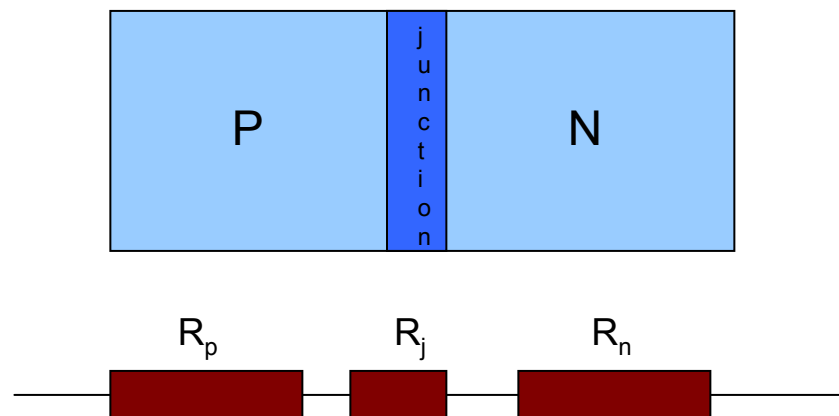
Junction Diode

- **Avalanche Breakdown**

Avalanche breakdown is a current multiplication process that occurs only in strong electric fields. Under high reverse bias voltage the electric field across the narrow junction region can become large enough to ionise (strip electrons) from semiconductor atoms. Field strengths used in semiconductor devices that exploit the avalanche effect are often in the 20–40 MV/m range. In devices that exploit the avalanche effect, the electric field is normally kept just below the threshold at which avalanche breakdown is possible, resulting in a current that is highly dependent on the generation of free electrons. In avalanche photodiodes, for example, incoming light is used to generate these free electrons.

- **Voltage drop (Turn-on voltage)**

Regions of the p-n diode which are not part of the junction can add resistance and cause a voltage drop. Therefore the diode is not seen to 'turn-on' until a certain voltage is reached. Values can range from 0.8V for Si up to 2-3V for a GaN LED.





The
University
Of
Sheffield.

Junction Diode

